

adhesion between a wafer and a photoresist layer when the photoresist layer is deposited onto the wafer and that generates a process deteriorating gas; and

a bake unit installed in the production line, the bake unit being adapted to bake the wafer having the photoresist layer formed thereon, the baking being susceptible to operational failures if exposed to the process deteriorating gas,

wherein the adhesion unit is installed at a first position and the bake unit is installed at a second position, and

wherein clean air flows from the second position where the bake unit is installed to the first position where the adhesion unit is installed, to carry the process deteriorating gas away from the bake unit.

Please cancel claim 5 without prejudice or disclaimer.

REMARKS

Applicants gratefully acknowledge that the Examiner has allowed claims 1, 3, and 8-12.

Reexamination and reconsideration of the present application are requested.

Applicants have amended claim 4 and canceled claim 5. Accordingly, claims 1, 3-4 and 6-12 remain pending in the application.

35 U.S.C. § 103

The Office Action rejected the previously-pending claims 4-7 under 35 U.S.C.